Surface Mount General Purpose Silicon Rectifiers

Parameter	Value	Unit
V_{RRM}	800~1000	V
$I_{F(AV)}$	8.0	A

DC-214AB/SMC

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place

Applications

- For use in general purpose rectification in power supplies, inverters, converters, and as freewheeling diodes for consumer and telecommunications applications.

Absolute Maximum Ratings and Characteristics (Ta=25℃ unless otherwise noted)

Parameter	Symbol	S8K	S8M	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	800	1000	V
Maximum RMS voltage	V_{RMS}	560	700	V
Maximum DC Blocking Voltage	V_{DC}	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	8.0		A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	200		A
Maximum Instantaneous Forward Voltage at 8A	V_F	0.985		V
Maximum DC Reverse Current Ta = 25℃ at Rated DC Blocking Voltage Ta = 125℃	I_R	10 250		μA
Typical Junction Capacitance (1)	C_j	40		pF
Typical Thermal Resistance (2)	$R_{\theta JA}$ $R_{\theta JC}$	35 13		℃/W
Operating and Storage Temperature Range	T_j , T_{stg}	-55 ~ +150		℃

（1）Measured at 1 MHz and applied reverse voltage of 4 VD.C
（2）P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Typical characteristics

Fig.1 Forward Current Derating Curve

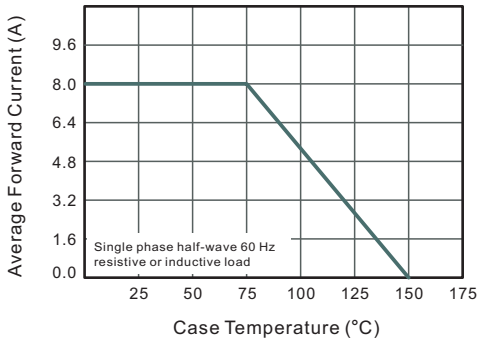


Fig.2 Typical Reverse Characteristics

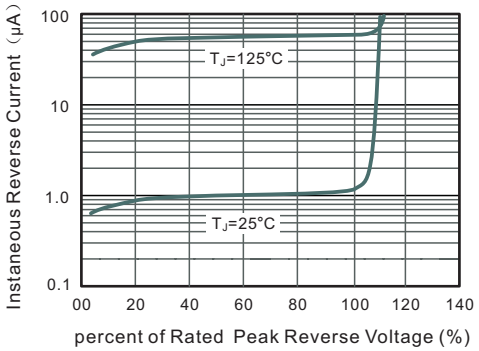


Fig.3 Typical Forward Characteristic

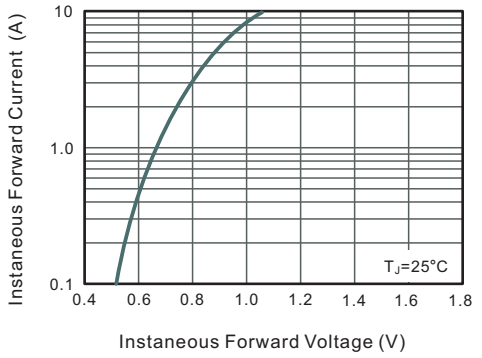


Fig.4 Typical Junction Capacitance

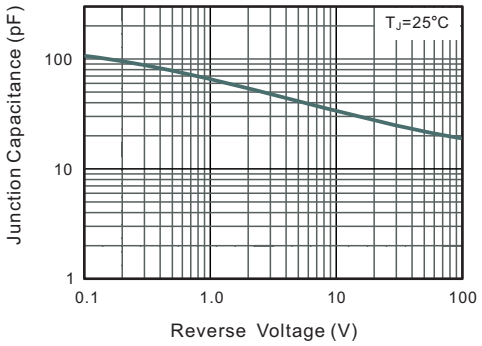
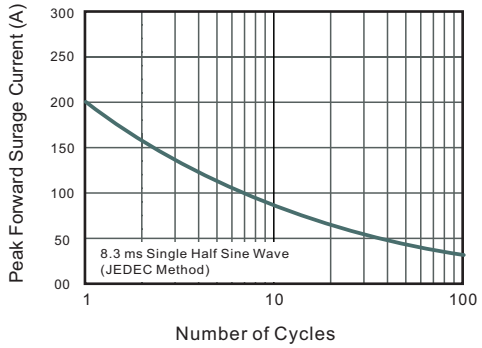


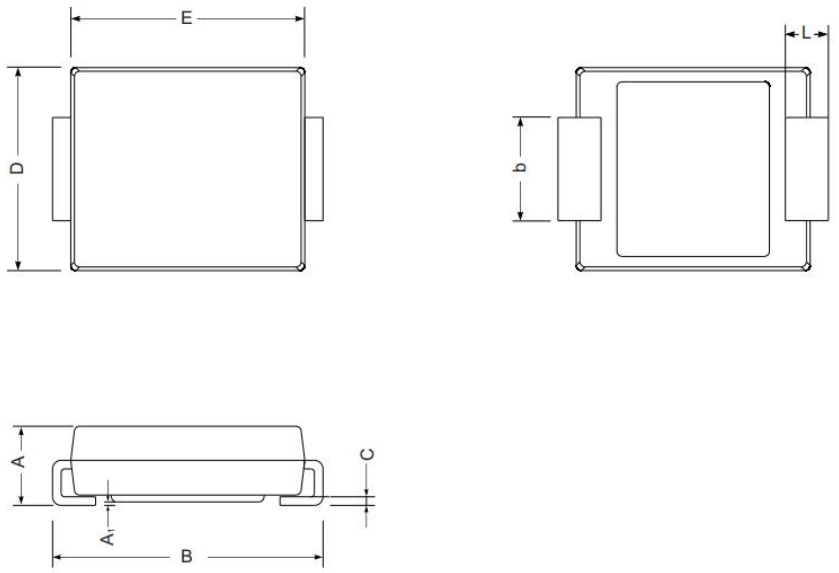
Fig.6 Maximum Non-Repetitive Peak Forward Surage Current



Package Outlines

Plastic surface mounted package; 2 leads

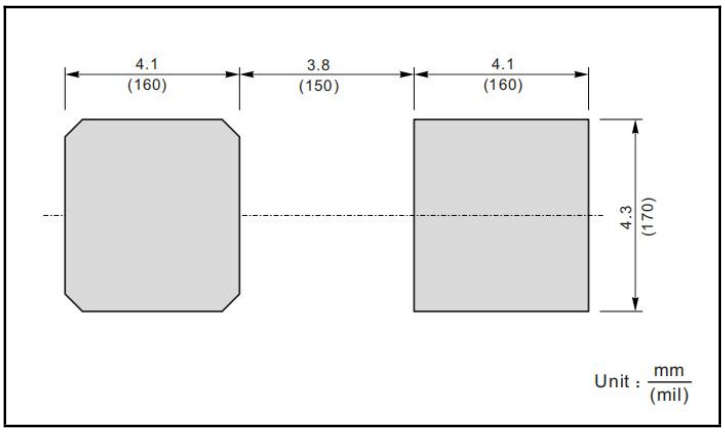
DO-214AB/SMC



SMC mechanical data

UNIT		A	E	D	B	A_1	C	L	b
mm	max	2.62	7.1	6.2	8.3	0.21	0.31	1.6	3.25
	min	2.00	6.6	5.6	7.7	0.05	0.15	0.9	2.75
mil	max	103	280	244	327	8.3	12	63	128
	min	79	260	220	303	2.0	5.9	35	108

The recommended mounting pad size



Marking

Type number	Marking code
S8K	S8K
S8M	S8M

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